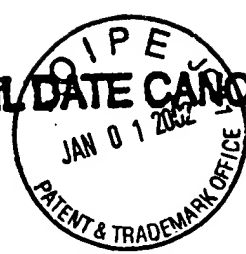


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VERSION WITH MARKINGS TO SHOW CHANGES MADE

In the Claims:

Please amend the following claims:

37. (Amended) A package for an integrated circuit die comprising:

a metal die pad and a plurality of metal contacts,

wherein said die pad has a first surface, and each said contact has a first end

facing the die pad, a ~~severed~~ second end opposite the first end, a first surface, a

second surface opposite the first surface, and a lip at the first surface of the contact

fully around a circumference of the contact except at the second end ~~surface~~;

an integrated circuit die on the die pad;

a plurality of conductors each electrically connected between the die and the first surface
of a respective one of the contacts; and

a package body formed of an encapsulant material, said encapsulant material covering the
die and underfilling the lip of the contacts, wherein the second surface of each said contact is
exposed at a horizontal first exterior surface of the package body.

43. (Amended) The package of claim 37, wherein the package body includes orthogonal
exterior side surfaces adjacent to the first exterior surface of the package body, and the second end
~~surface~~ of each contact is exposed in a common plane with one of the exterior side surfaces of the
package body.

44. (Amended) A package for an integrated circuit die comprising:

a metal die pad and a plurality of metal contacts,

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wherein said die pad has a first surface, a second surface, and a peripheral side surface around a circumference of the die pad between the first and second surfaces, said side surface including a central depression fully around the circumference of the die pad, and

wherein each said contact has a first end facing the die pad, a ~~severed~~ second end opposite the first end, a planar first surface, a second surface opposite the first surface, and opposing side surfaces between the first and second ~~end surfaces~~ ends and the first and second surfaces, the first surface of the contact is in a horizontal plane with the first surface of the die pad, and the first end ~~surface~~ and the opposing side surfaces of the contact include a central depression;

an integrated circuit die on the first surface of the die pad;

a plurality of conductors each electrically connected between the die and the first surface of a respective one of the contacts; and

a package body formed of an encapsulant material,

wherein the encapsulant material covers the die and fills the central depression of the side surface of the die pad and the central depression of the first end ~~surface~~ and side surfaces of the contacts, and the second surface of the contacts is exposed at a first exterior surface of the package body.

45. (Amended) The package of claim 44, wherein the side surfaces of the die pad and the side surfaces and first end ~~surface~~ of the contacts further include numerous asperities, said asperities being covered with the encapsulant material.

46. (Amended) The package of claim 44, wherein the package body includes orthogonal exterior side surfaces adjacent to the first exterior surface of the package body, and the second end ~~surface~~ of each contact is exposed in the common plane with one of the exterior side surfaces of the package body.

47. (Amended) A package for an integrated circuit die comprising:

a metal die pad and a plurality of metal contacts,

wherein said die pad has a first surface, a second surface, and a peripheral side surface around a circumference of the die pad between the first and second surfaces, said side surface including a protruding central peak fully around a circumference of the die pad, and

wherein each said contact has a first end facing the die pad, a ~~severed~~ second end opposite the first end, a first surface, a second surface opposite the first surface, and opposing side surfaces between the first and second ~~end-surfaces~~ ends and the first and second surfaces, and the first end ~~surface~~ and the opposing side surfaces of the contact include a protruding central peak;

an integrated circuit die on the first surface of the die pad;

a plurality of conductors each electrically connected between the die and the first surface of one of the contacts; and

a package body of an encapsulant material,

wherein the encapsulant material covers the die, and the protruding central peak of the side surface of the die pad and of the first end ~~surface~~ and side surfaces

of the contacts extends into the encapsulant material, and the second surface of the contacts is exposed at a first exterior surface of the package body.

50. (Amended) The package of claim 47, wherein the side surface of the die pad and the side surfaces and first end ~~surface~~ of the contacts further include numerous asperities on said protruding central peak.

51. (Amended) The package of claim 47, wherein the package body includes orthogonal exterior side surfaces adjacent to the first exterior surface of the package body, and the second end ~~surface~~ of each contact is exposed in a common plane with one of the exterior side surfaces of the package body.

53. (Amended) A package for an integrated circuit die comprising:

a metal die pad and a plurality of metal contacts,

wherein said die pad has a first surface, a second surface opposite the first surface, and a peripheral side surface around a circumference of the die pad between the first and second surfaces, and

wherein each said contact has a first end facing the die pad, a ~~severed~~ second end opposite the first end, a first surface in a horizontal plane with the first surface of the die pad, a second surface opposite the first surface of the contact, and opposing side surfaces between the first and second ~~end-surfaces~~ ends and the first and second surfaces of the contact;

an integrated circuit die on the first surface of the die pad;

a plurality of conductors each electrically connected between the die and the first surface

of one of the contacts; and

a body formed of an encapsulant material, wherein the encapsulant material covers the die and the second surface of the contacts is exposed at an exterior surface of the package body, and

wherein the side surface of the die pad includes a means around the circumference of the die pad for vertically locking the die pad to the encapsulant material, and the side surfaces and first end ~~surface~~ of the contacts include a means for vertically locking the contact to the encapsulant material.

55. (Amended) The package of claim 53, wherein the side surfaces of the die pad and the side surfaces and first end ~~surface~~ of the contacts further include numerous asperities that are covered with the encapsulant material.

56. (Amended) The package of claim 53, wherein the package body includes orthogonal exterior side surfaces adjacent to the first exterior surface of the package body, and the second end ~~surface~~ of each contact is exposed in a common plane with one of the exterior side surfaces of the package body.

61. (Amended) The package of claim 57, wherein the package body includes orthogonal exterior side surfaces adjacent to the first exterior surface of the package body, and a ~~severed~~ distal end of each contact is exposed in a common plane with one of the exterior side surfaces of the package body.